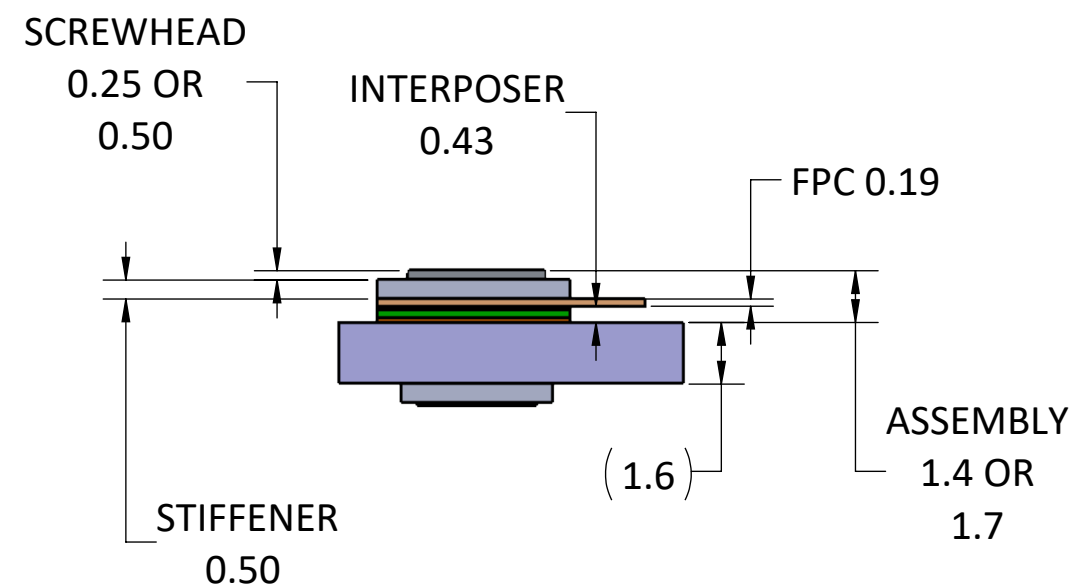
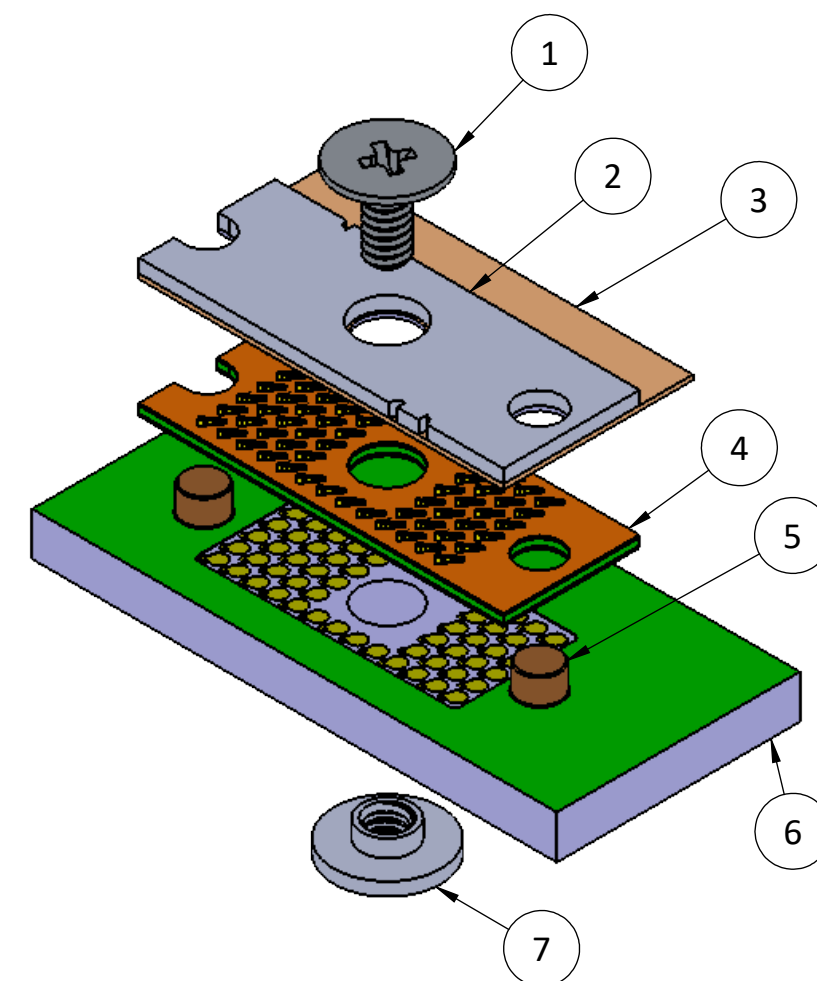
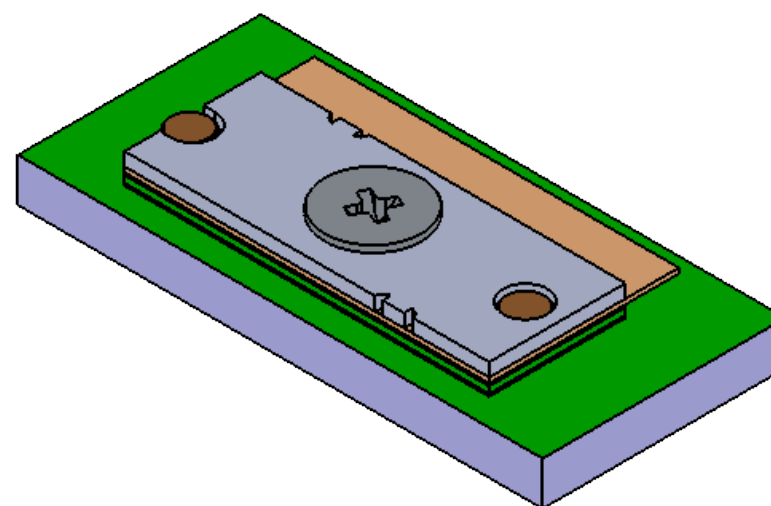
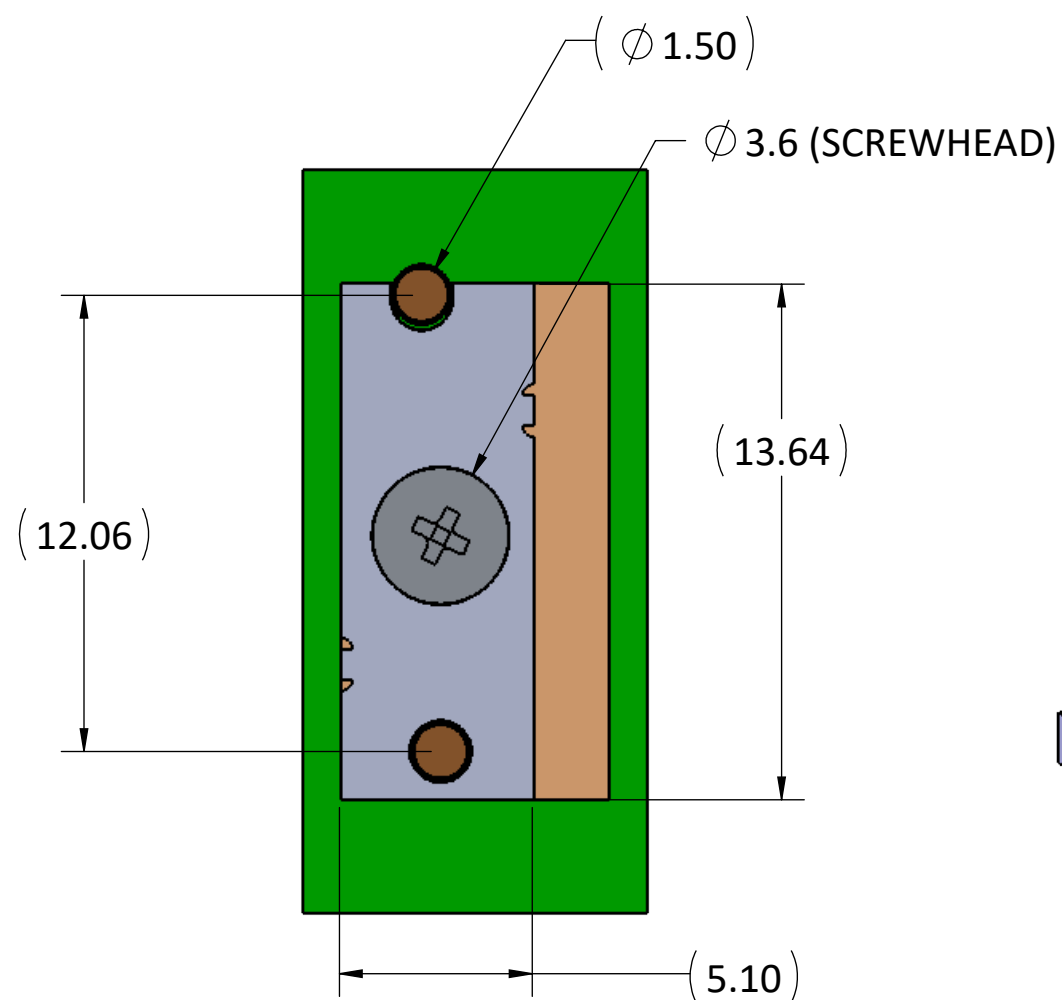


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REVISIONS				
REV	ECN	DESCRIPTION	DATE	APPROVED
A	1231	PRODUCTION RELEASE	04/10/2019	WES TAO
B	1277	CHANGED TO PHILLIPS HEAD SCREW	10-30-2020	WES TAO
C	1285	ADDED STIFFENER BREAK TABS	03-01-2021	WES TAO



ITEM	DESCRIPTION	NEOCONIX P/N	QTY per ASSY
1*	SCREW, M1.4, L=3MM	B01-000614	1
	SCREW, M1.4, L=4MM	B01-000657	
	SCREW, M1.4, L=5MM	B01-000658	
2	STIFFENER	LPM-062A-STF	1
3	FPC	CUSTOM UPON REQUEST	1
4	INTERPOSER	LPM-062A	1
5	ALIGNMENT PIN	B01-000589	2
6	PCB	N/A - CUSTOMER SUPPLIED	1
7	SMT NUT, M1.4	B01-000581	1

\* SEE AS-000021 FOR RECOMMENDED SCREW LENGTH.  
ALL ITEMS ORDERED SEPARATELY.

<p>4020 MOORPARK AVENUE #108 SAN JOSE, CA 95117 TEL: 408-530-9393 FAX: 408-530-9383</p>	<p>DIMENSIONS ARE IN MM [INCH]</p> <p>.X ± .XX ± .XXX ±</p> <p>ANGLE: NO DEC ± .X ± .XX ±</p> <p>THIRD ANGLE</p>	MATERIAL:		TITLE:		
		FINISH:		LPM ASSEMBLY 62 POSITIONS LGA-LGA		REV
		DRAWN BY: JASON WU	03-20-2015	SIZE	DWG NUMBER:	C
		CHECKED BY:		B+	LPM-062A-ASY	
ENGR APPR:		SCALE: 5:1		SHEET 1 OF 5		
MFG APPR:						
QA APPR:						

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REVISIONS				
REV	ECN	DESCRIPTION	DATE	APPROVED
A	1231	PRODUCTION RELEASE	04/10/2019	WES TAN

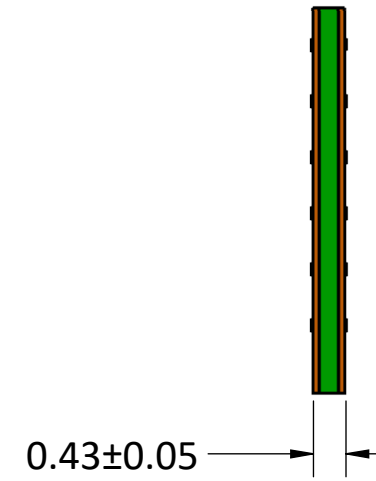
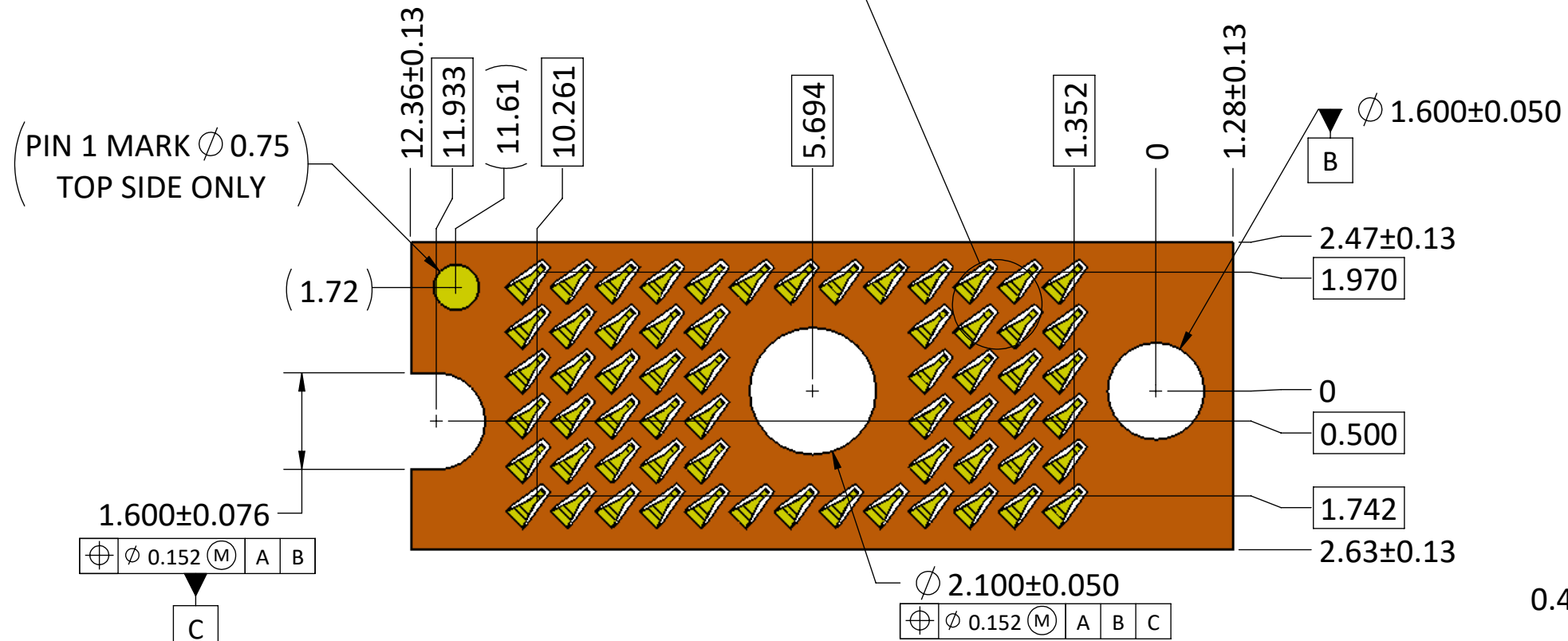
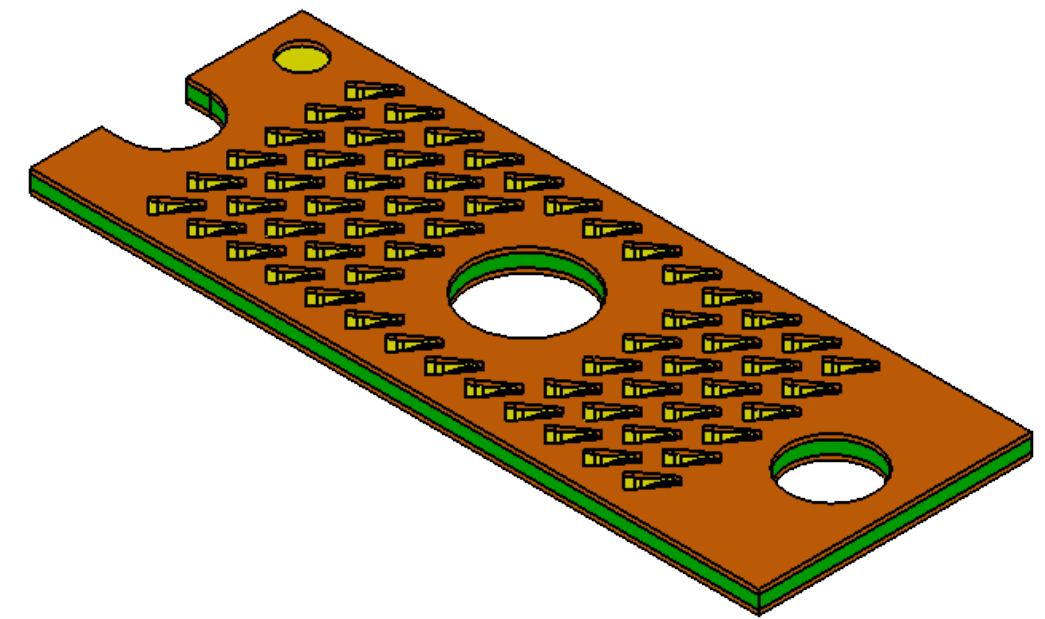
4 62 POSITIONS TOP  
62 POSITIONS BOTTOM

⊕ ∅ 0.203 A B C

PITCH  
0.7424

PITCH  
0.7424

DETAIL B  
SCALE 20 : 1



**COMPRESSED**

**UNCOMPRESSED**

NOTES (UNLESS OTHERWISE SPECIFIED):

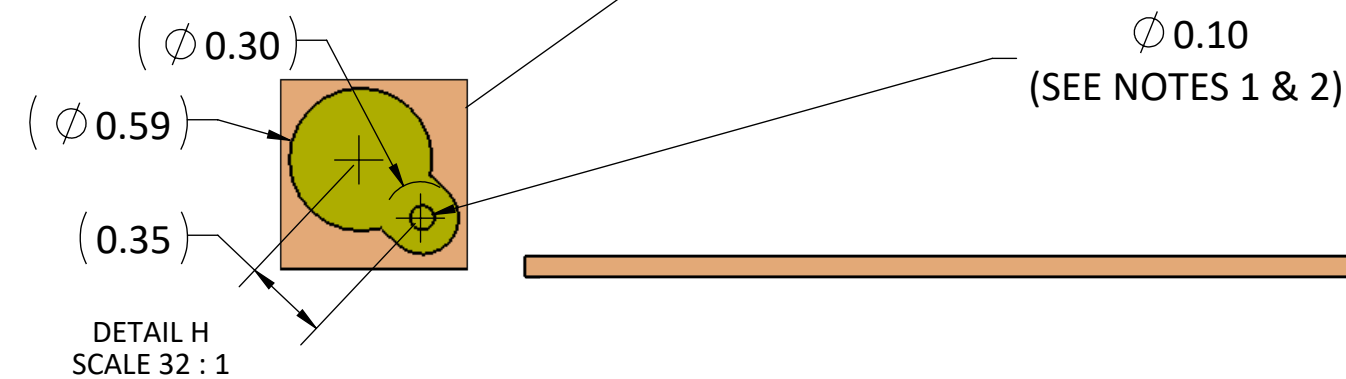
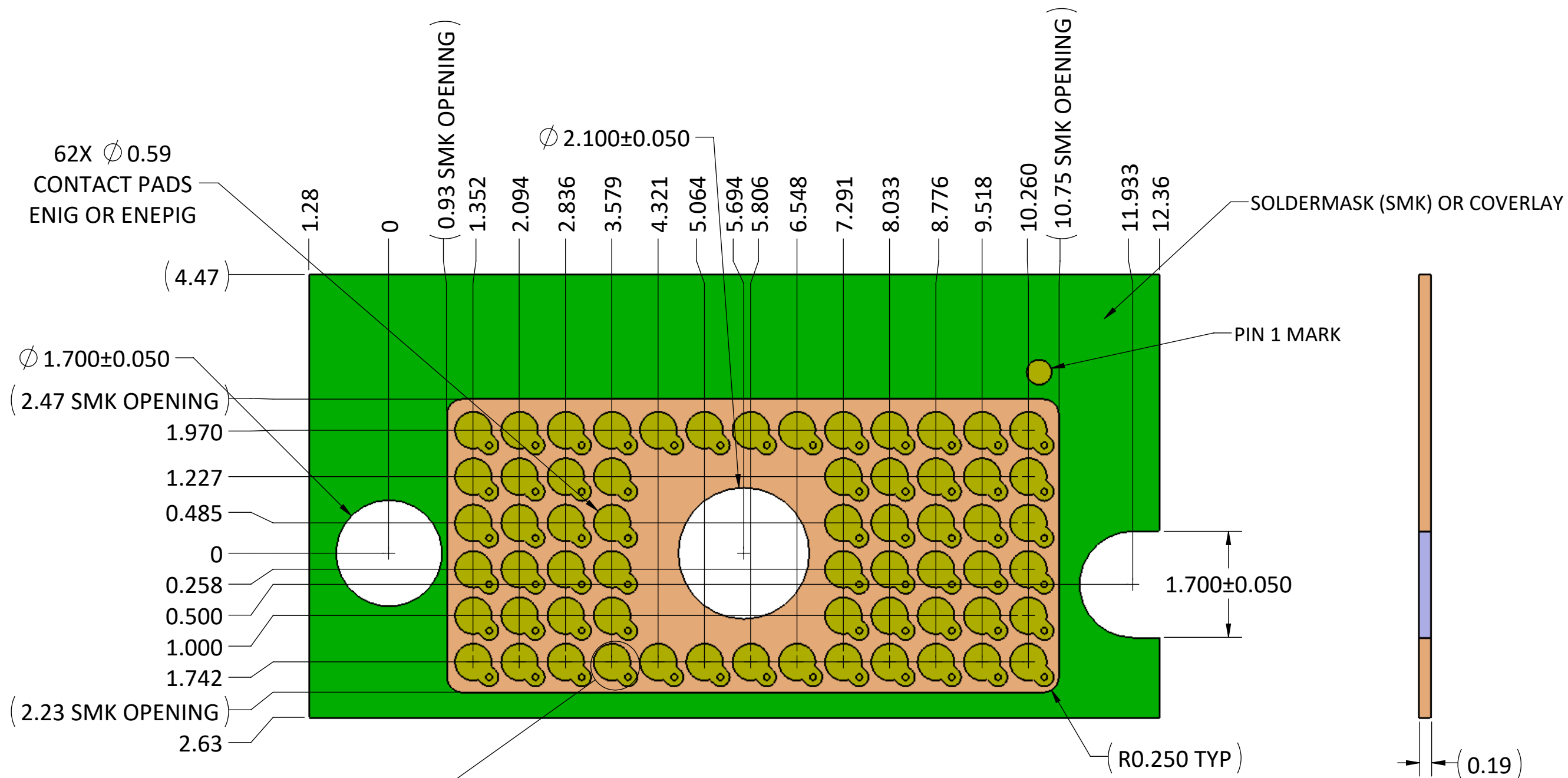
1. INTERPRET DRAWING PER ASME Y14.5M-1994.
2. HALOGEN-FREE PER IPC-4101B.
3. COMPLIANT WITH RoHS DIRECTIVE 2011/65/EU.

4 CENTER MARKS OF CONTACT POSITIONS ARE FOR COMPRESSED STATE

<p>4020 MOORPARK AVENUE #108 SAN JOSE, CA 95117 USA TEL: 408-530-9393 FAX: 408-530-9383</p>	<p>DIMENSIONS ARE IN MM [INCH]</p> <p>.X ± 0.13 [.005] .XX ± 0.08 [.003] .XXX ± 0.025 [.001]</p> <p>ANGLE: NO DEC ± 1° .X ± 0.5° .XX ± 0.25°</p> <p>THIRD ANGLE</p>	<p>MATERIAL: SEE NOTES</p> <p>FINISH: SEE NOTES</p> <p>DRAWN BY: Jason Wu 03-20-2015</p> <p>CHECKED BY: Woody Maynard 03-20-2015</p> <p>ENGR APPR:</p> <p>MFG APPR:</p> <p>QA APPR:</p>	<p>TITLE: <b>LPM INTERPOSER 62 POSITIONS LGA-LGA</b></p> <p>SIZE: B+</p> <p>DWG NUMBER: <b>LPM-062A</b></p> <p>SCALE: 10:1</p>	
	<p>REV: A</p>	<p>DATE: 04/10/2019</p>	<p>APPROVED: WES TAN</p>	<p>REV: A</p>
	<p>0.30</p>	<p>0.18 +0.12 / -0.08 BOTH SIDES</p>	<p>0.43±0.05</p>	<p>10:1</p>
	<p>0.30</p>	<p>0.18 +0.12 / -0.08 BOTH SIDES</p>	<p>0.43±0.05</p>	<p>10:1</p>

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REVISIONS				
REV	ECN	DESCRIPTION	DATE	APPROVED
A	1231	PRODUCTION RELEASE	04-10-2019	WES TAN



NOTES:

1. THE PAD GEOMETRY SHOWN ASSUMES A BLIND VIA STACK-UP. IF A THRU-HOLE VIA IS NEEDED, IT IS ACCEPTABLE TO ROTATE THE POSITION OF THE VIAS AS NEEDED TO AVOID INTERFERENCE WITH THE BACK SIDE NUT SOLDER PAD.
2. IF THE VIA NEEDS TO BE LOCATED WITHIN THE 0.59MM PAD DIAMETER, IT MUST BE FILLED, PLATED, AND PLANARIZED WITH 25UM MAX DIMPLE.

**neconix**  
4020 MOORPARK AVENUE #108  
SAN JOSE, CA 95117 USA  
TEL: 408-530-9393 FAX: 408-530-9383

DIMENSIONS ARE IN  
MM [INCH]  
.X  $\pm 0.13$  [.005]  
.XX  $\pm 0.08$  [.003]  
.XXX  $\pm 0.025$  [.001]  
ANGLE: NO DEC  $\pm 1^\circ$   
.X  $\pm 0.5^\circ$   
.XX  $\pm 0.25^\circ$

MATERIAL:  
FINISH:  
DRAWN BY: JASON WU 03-20-2015  
CHECKED BY:  
ENGR APPR:  
MFG APPR:  
QA APPR:

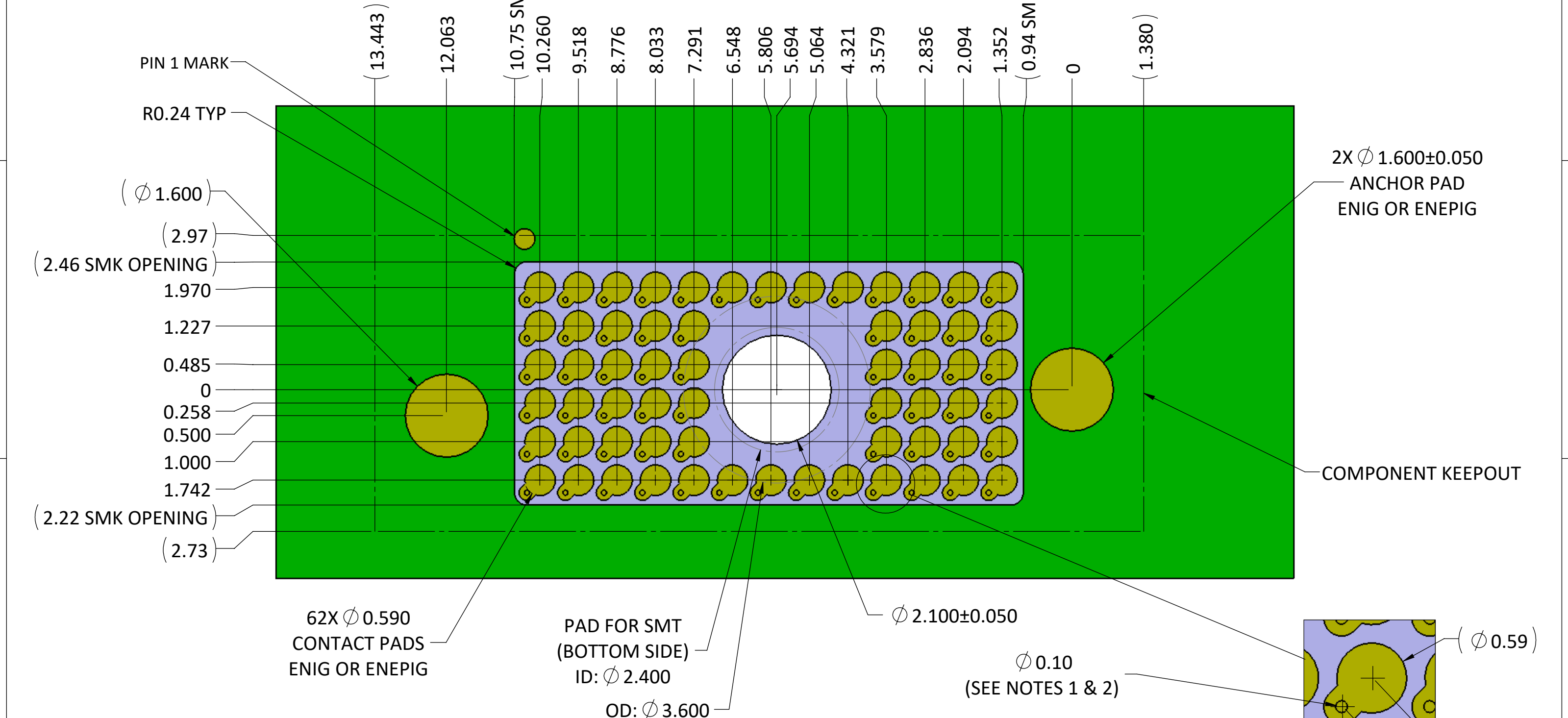
TITLE:  
**RECOMMENDED FPC LAYOUT  
LPM 62 POSITIONS**

SIZE: B+ DWG NUMBER: LPM-062A-FPC REV: A

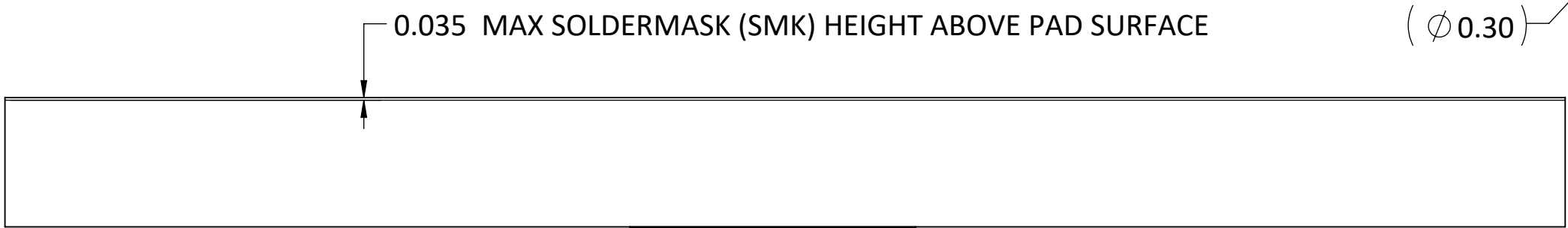
SCALE: 10:1 SHEET 3 OF 5

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REVISIONS				
REV	ECN	DESCRIPTION	DATE	APPROVED
A	1231	PRODUCTION RELEASE	04/10/2019	WES TAN



- NOTES:
1. THE PAD GEOMETRY SHOWN ASSUMES A BLIND VIA STACK-UP. IF A THRU-HOLE VIA IS NEEDED, IT IS ACCEPTABLE TO ROTATE THE POSITION OF THE VIAS AS NEEDED TO AVOID INTERFERENCE WITH THE BACK SIDE NUT SOLDER PAD.
  2. IF THE VIA NEEDS TO BE LOCATED WITHIN THE 0.59MM PAD DIAMETER, IT MUST BE FILLED, PLATED, AND PLANARIZED WITH 25UM MAX DIMPLE.

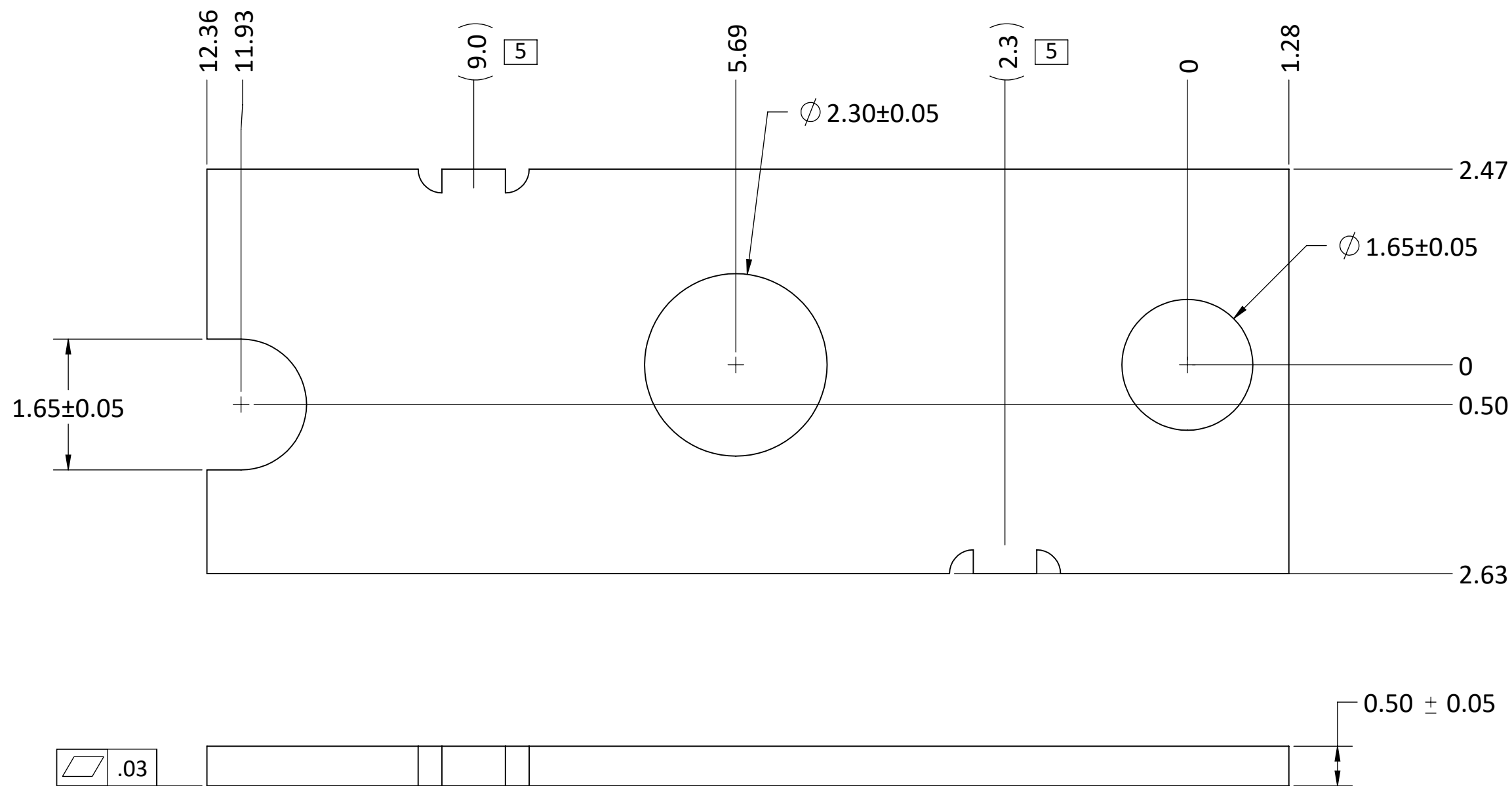


<p>4020 MOORPARK AVENUE #108 SAN JOSE, CA 95117 USA TEL: 408-530-9393 FAX: 408-530-9383</p>	<p>DIMENSIONS ARE IN MM [INCH]</p> <p>.X ± 0.13 [.005] .XX ± 0.08 [.003] .XXX ± 0.025 [.001]</p> <p>ANGLE: NO DEC ± 1° .X ± 0.5° .XX ± 0.25°</p> <p>THIRD ANGLE</p>	<p>MATERIAL:</p> <p>FINISH:</p> <p>DRAWN BY: JASON WU 03-20-2015</p> <p>CHECKED BY:</p> <p>ENGR APPR:</p> <p>MFG APPR:</p> <p>QA APPR:</p>	<p>TITLE: <b>RECOMMENDED PCB LAYOUT LPM 62 POSITIONS</b></p> <p>SIZE: B+</p> <p>DWG NUMBER: <b>LPM-062A-PCB</b></p> <p>SCALE: 10:1</p>
	<p>REV: A</p>		<p>DATE: 04/10/2019</p>

SHEET 4 OF 5

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REVISIONS				
REV	ECN	DESCRIPTION	DATE	APPROVED
A	1231	PRODUCTION RELEASE	04/10/2019	WES TAO
B	1285	ADDED BREAK TABS, STD TOLS	03-01-2021	WES TAO



NOTES (UNLESS OTHERWISE SPECIFIED):

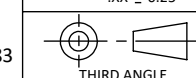
1. INTERPRET DRAWING PER ASME Y14.5M-1994.
2. USE THERMOSETTING ADHESIVE FILM TO ATTACH TO FPC.
3. RECOMMEND 0.15MM CLEARANCE BETWEEN EDGE OF ADHESIVE AND EDGE/HOLE FEATURES TO ACCOMODATE ADHESIVE FLOW.
4. MATERIAL: 301 SS FULL HARD
5. BREAK APPROXIMATELY AS SHOWN: NOT TO EXTEND BEYOND EDGE OF STIFFENER



4020 MOORPARK AVENUE #108  
SAN JOSE, CA 995117 USA  
TEL: 408-530-9393 FAX: 408-530-9383

DIMENSIONS ARE IN MM

.X ± 0.13  
.XX ± 0.08  
.XXX ± 0.025  
ANGLE: NO DEC ± 1°  
.X ± 0.5°  
.XX ± 0.25°



MATERIAL:	SEE NOTES
FINISH:	SEE NOTES
DRAWN BY:	JASON WU 07-31-2015
CHECKED BY:	
ENGR APPR:	
MFG APPR:	
QA APPR:	

TITLE:		STIFFENER, LPM 62 POS	
SIZE:	B+	DWG NUMBER:	LPM-062A-STF
REV:	B	SCALE:	10:1
		SHEET	5 OF 5